

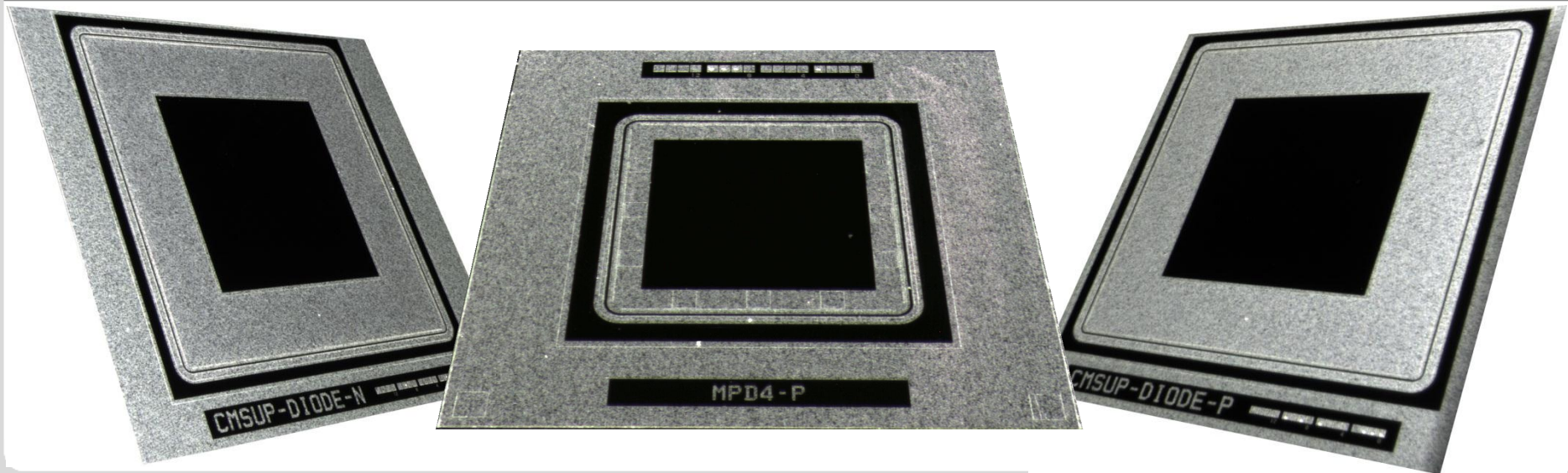
First CCE and TCT measurements on irradiated diodes of the CMS-HPK-Campaign

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Robert Eber

A. Dierlamm, Th.Müller, W. de Boer, P. Steck, Th. Pöhlsen (HH), Ch. Scharf (HH)

Institut für Experimentelle Kernphysik

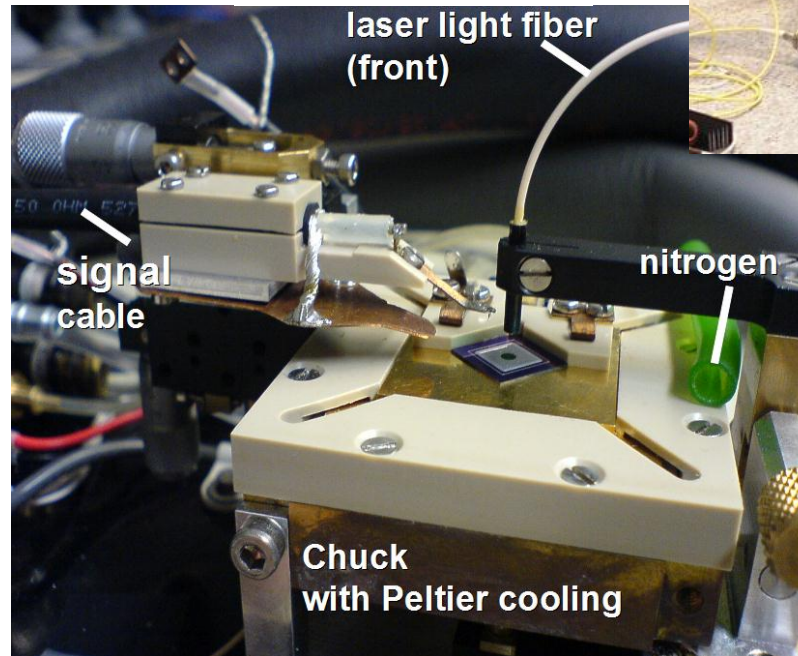
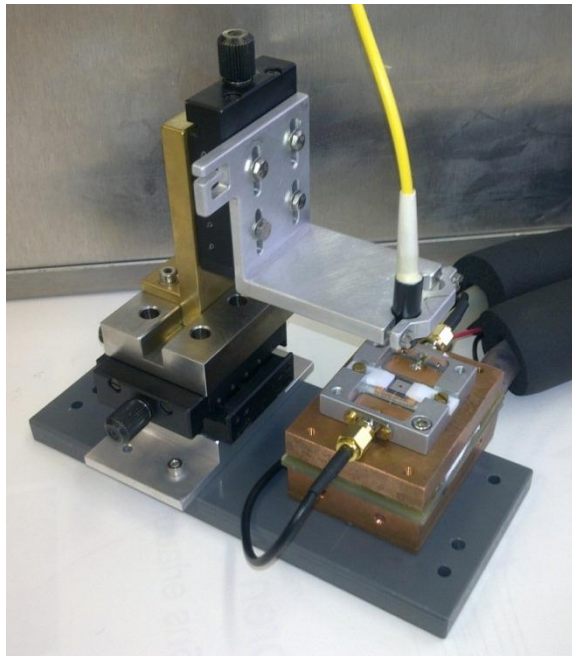
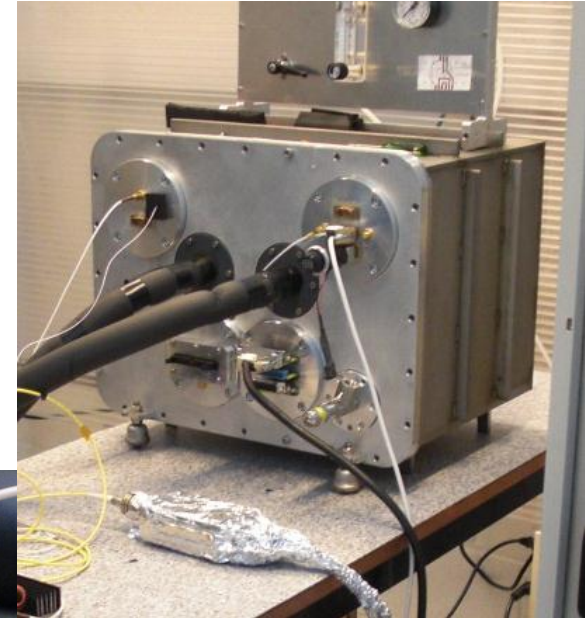


Outline

- Setups and Groups
- Preparation for TCT and CCE measurements
- Stability measurements
 - Backside measurements with 880nm
 - Comparison of FZ / MCz material
- Charge Collection of non-irradiated diodes
- CCE of irradiated diodes
- TCT of irradiated diodes
 - Trapping times
- Conclusion and Outlook

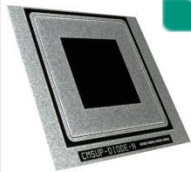
Setups for CCE and TCT measurements

- Institutes involved in diode measurements
 - CERN, Hamburg, Louvain, Karlsruhe



Specifications of CCE / TCT measurements

■ CCE measurements

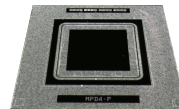


- Measurement of charge collection, simulation of a MIP

- Integrated signal important

■ TCT measurements

- Time resolved curves
- Observation of 1 charge carrier through the diode
- Needed for trapping times and electric field



■ Lasers:

- >1000nm for CCE
- Red for TCT (~680nm)
- 880nm for backside TCT

- Laser intensity < 100 MIPs

- Repetition rate 200Hz

- Min. 5GS/s Oscilloscope

- Averaging of waveforms > 500

■ Measurement steps:

- 0V-1000V in 10V steps

- No breakdown

- Non-irradiated diodes

- 20°C, 0°C, -20°C

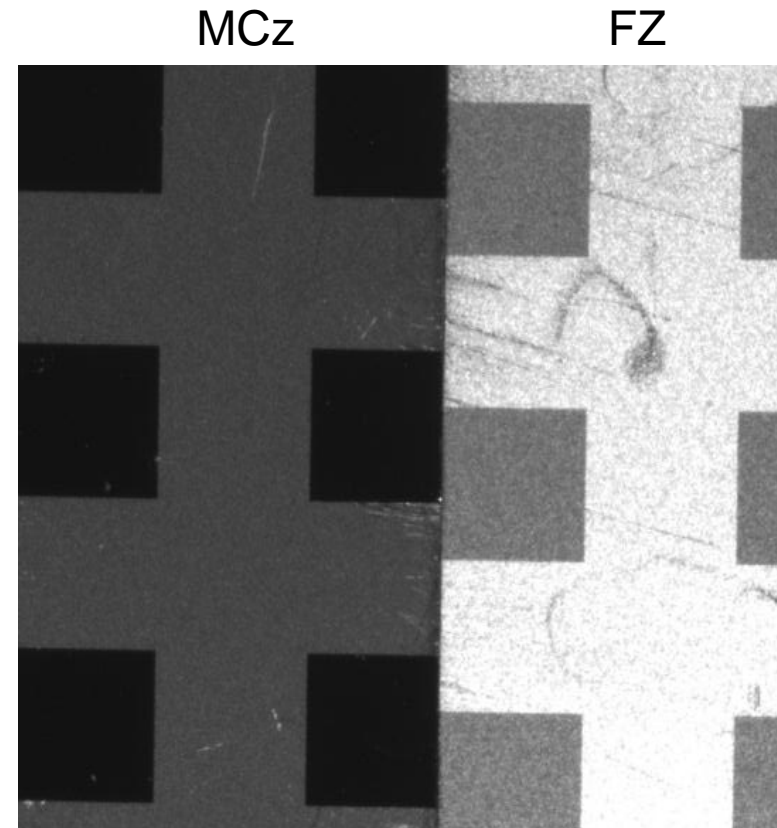
- Irradiated diodes

- 0°C, (-10°C), -20°C, (-30°C)

- Several annealing steps

Backside measurements

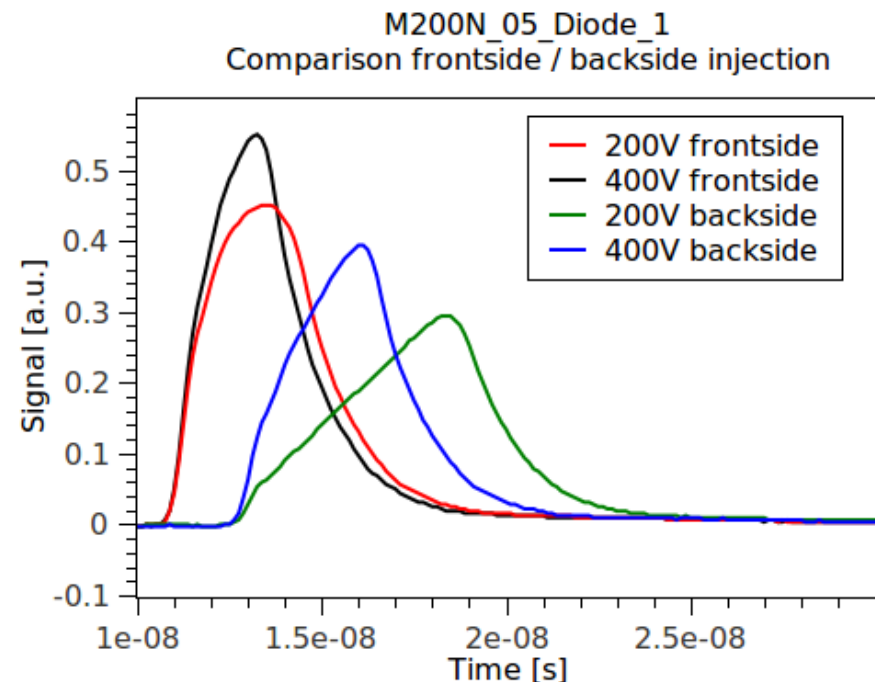
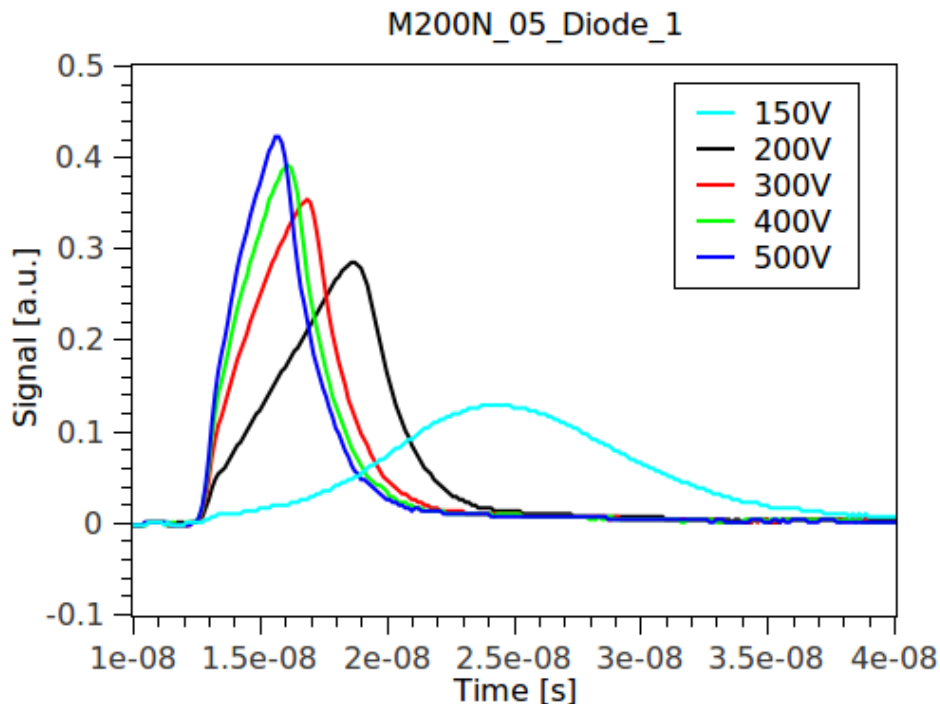
- Backside TCT measurements not possible on thin diodes because of deep diffusion
- Signal generation possible in
 - 320 μ m thick FZ diodes
 - 200 μ m MCz diodes
- Due to relatively deep backside implantation and backside properties on FZ diodes – generation of charge carriers not possible with red Laser (680nm) on FZ
- IR Laser light shot an FZ backside generates only ~20% of frontside signal



Backside measurements

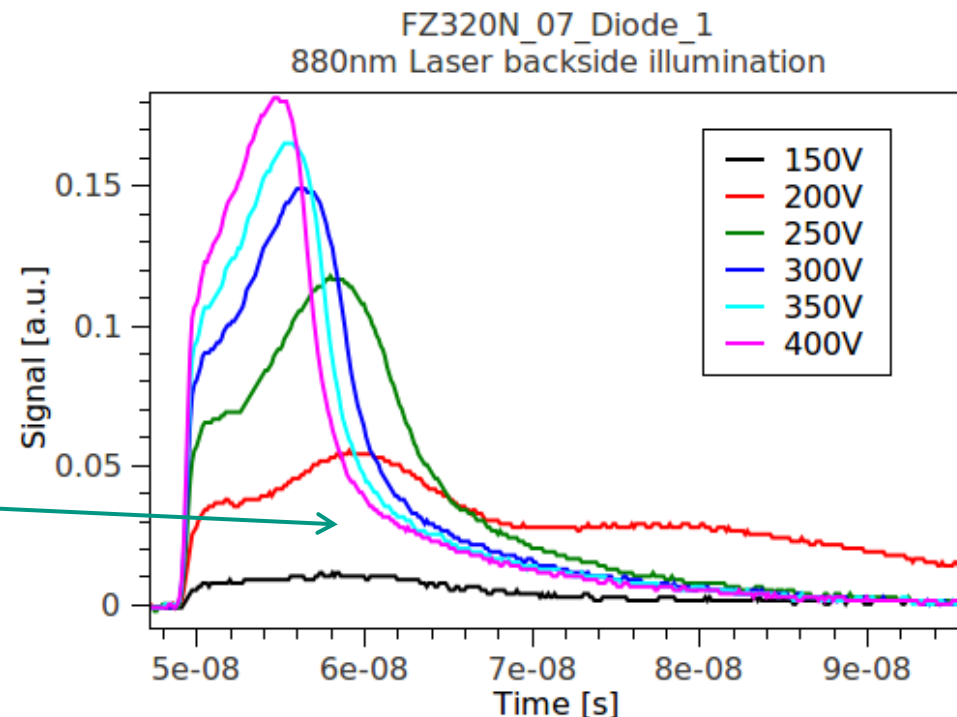
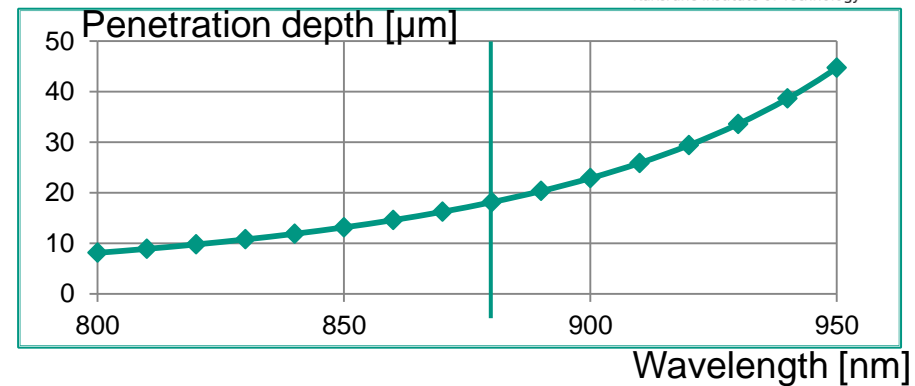
- Red Laser works well for MCz diodes
- Not a deep implantation on the backside – different processing

- Back/front charge collection ~ 80%
- For comparison, FZ material with a physical thickness of 200 μm is ordered and will arrive in autumn this year



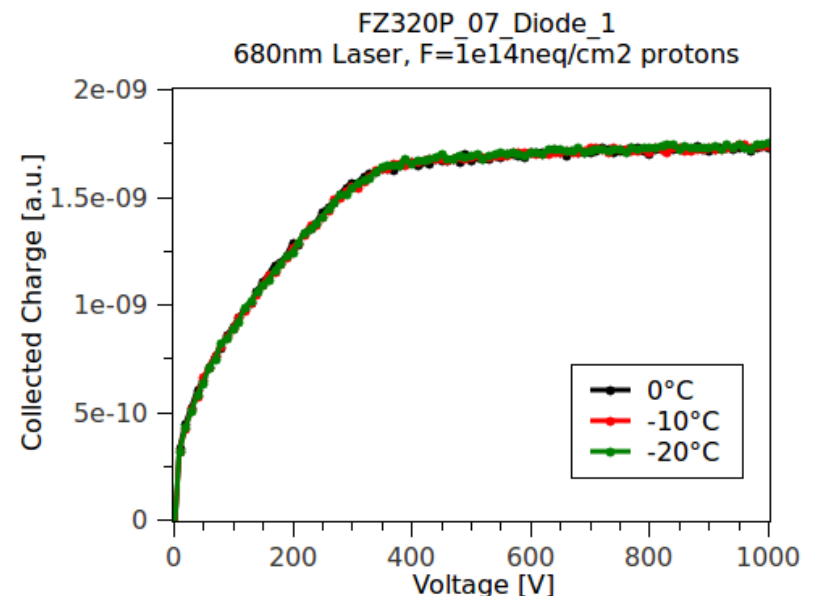
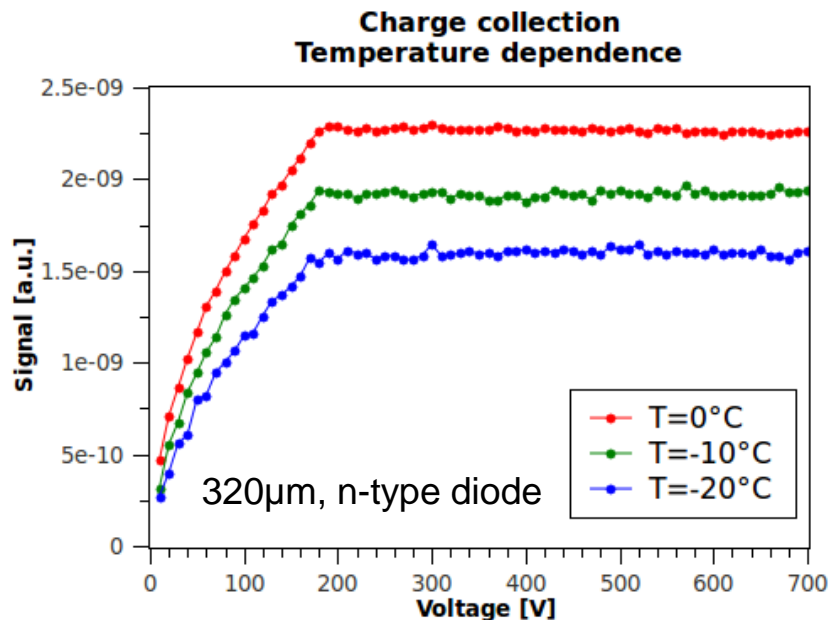
Backside measurements

- Use 880nm Laser for illumination on the backside for FZ material
- Signal looks almost like a *red* one
- Possibility to look at one charge carrier in FZ 320 μ m material
- At low voltages
 - Broad signal coming from diffusion out of the deep diffusion region
- At higher voltages
 - Long tails at the end of signal
- First small peak in signal due to electrons (n-type diode)
- Useful for analysis?



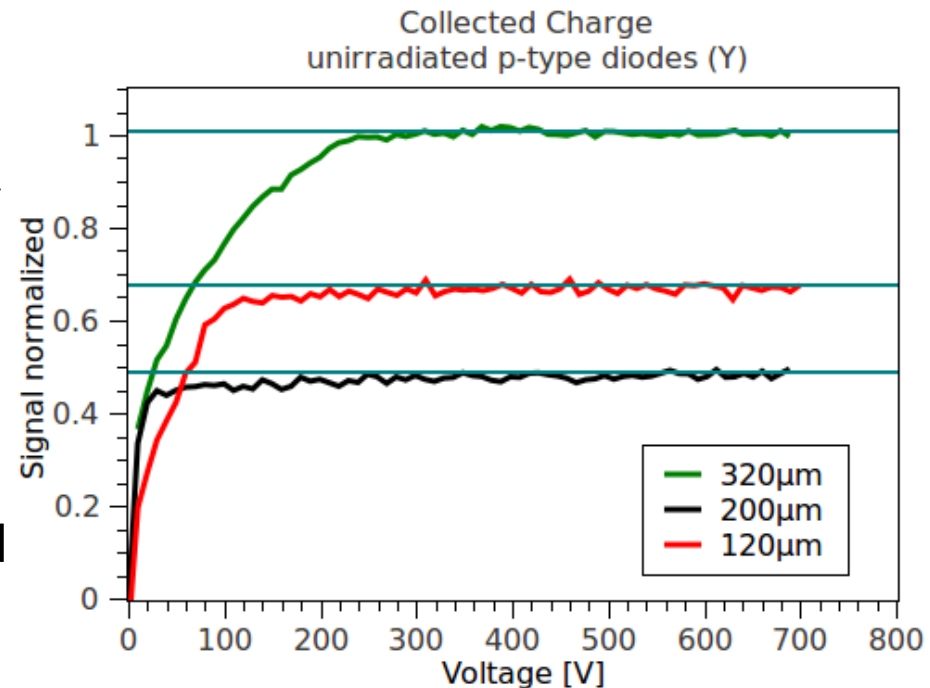
CCE measurement of unirradiated diodes

- Signal generation with infrared Laser (1055nm)
- Because of indirect bandgap in silicon, fewer charge carriers are produced
- Calibrate signal for different temperatures
- Red Laser always generates the same amount of charge carriers when shot on frontside (irradiated diode example)

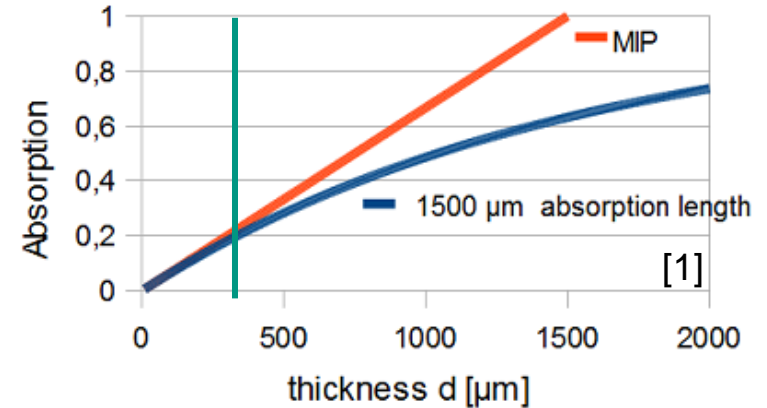
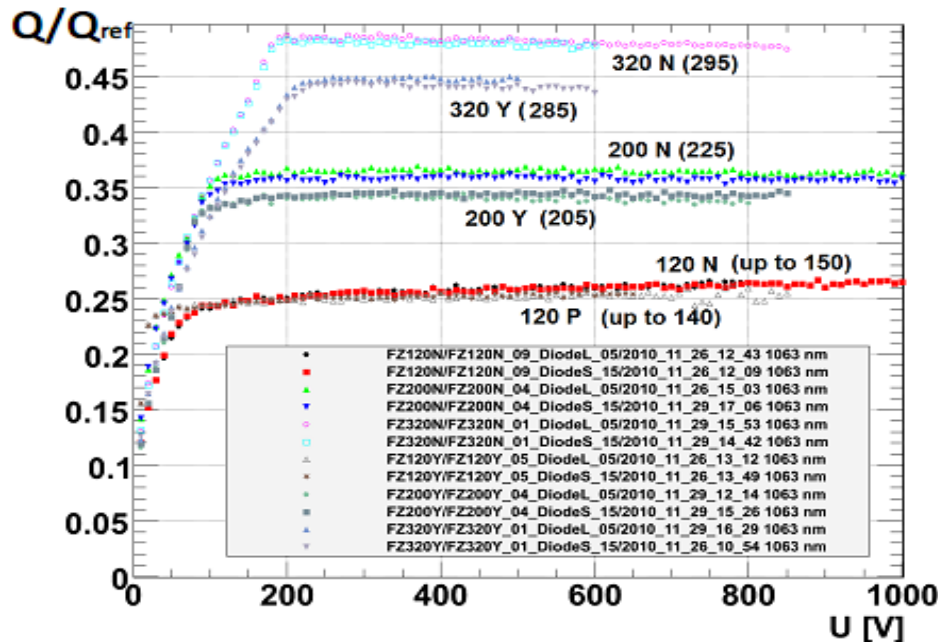


CCE measurement of unirradiated diodes

- Signal generation with infrared Laser (1055nm)
- CCE normalized to the 320 μm thick diode of same type
- Slight increase in CCE(V) seen for 200 μm and 120 μm thick diodes
 - Gain more active thickness due to deep diffusion at high voltages
- Charge collection ratio in expected range
 - 63% for 200 μm , (67% for 215 μm)
 - 38% for 120 μm , (45% for 145 μm)



Charge collection on different wafers



Collected charge compared on different types of wafers. [1]

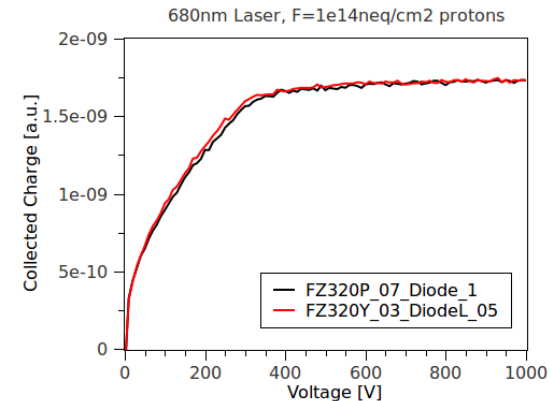
- Taking into account
 - Attenuation length of laser
 - Measured thickness from CV
- Deviations of max. 5% from mean value

diode	d_{max}	Absorption A	Q_{meas}	Q_{meas}/A	$Q/A / \text{mean}$
120N	150	0,1	0,26	2,732	1,02
200N	225	0,14	0,36	2,584	0,97
320N	295	0,18	0,48	2,689	1,01
120Y	140	0,09	0,25	2,806	1,05
200Y	205	0,13	0,34	2,662	1
320Y	285	0,17	0,45	2,572	0,96

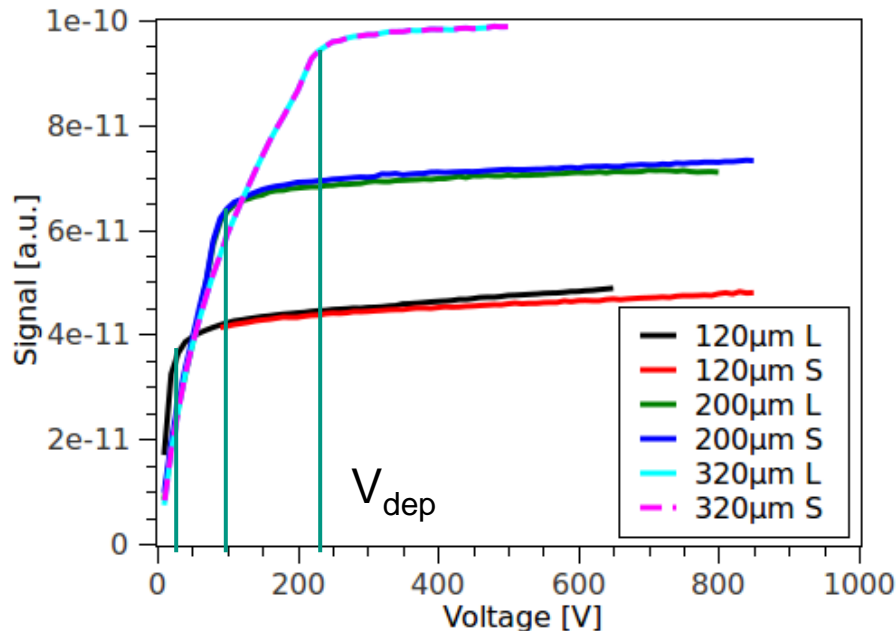
CCE measurement of irradiated diodes

- Deviations in charge collection between small and large diodes negligible
- After irradiation
 - Almost same charge collection seen between L and S

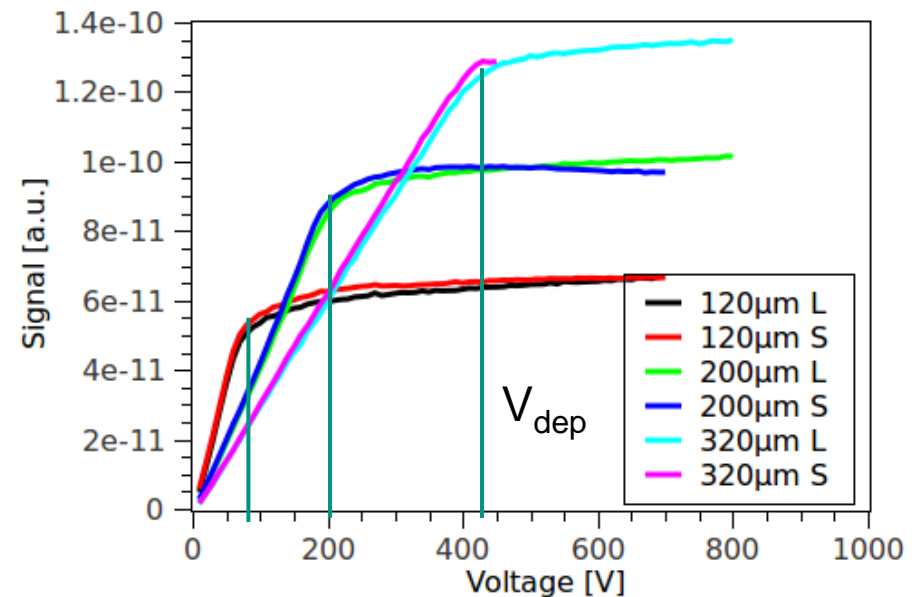
- Different irradiation step – same Charge collection



Charge collection unirradiated p-type diodes (Y)

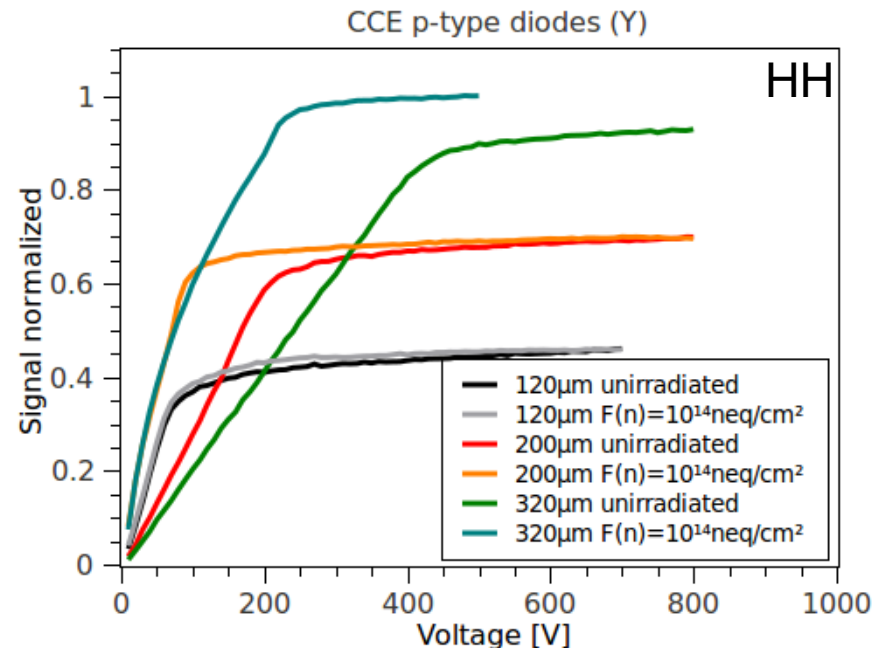
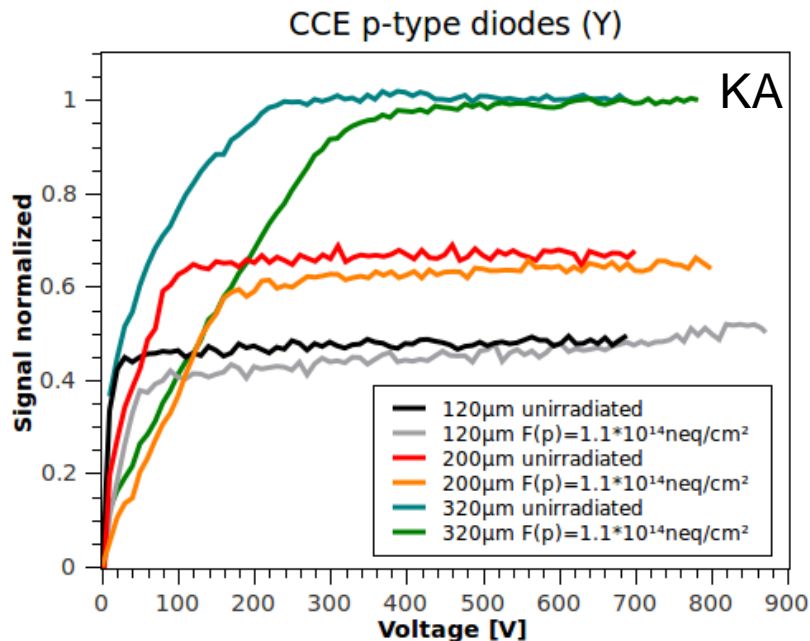


Charge collection neutron irradiated p-type diodes (Y)



CCE measurements of irradiated diodes

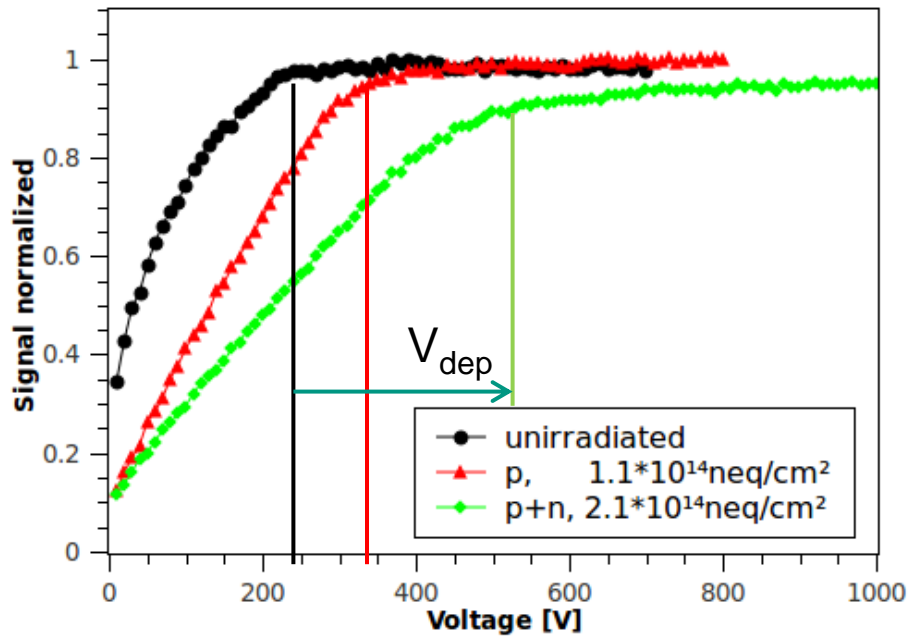
- Proton irradiated p-spray diodes reach 100% charge collection after irradiation
- Differences in charge collection of FZ200 μ m seen
 - Not same diode, different active thickness (not corrected)
- 120 μ m
 - Higher electric fields - Gain even more active thickness after irradiation



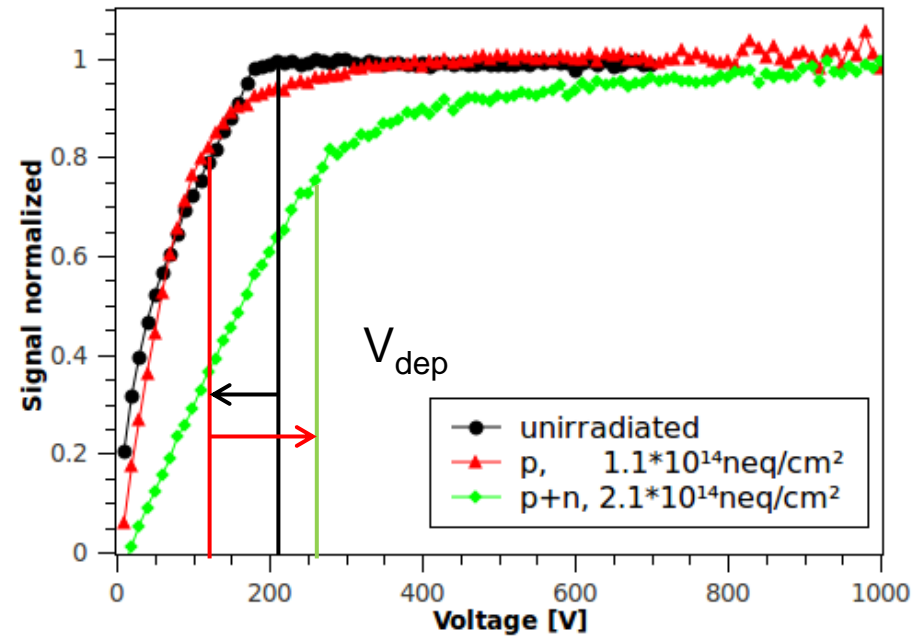
CCE measurement of irradiated diodes

- Comparison of 320 μm thick diodes at $T=0^\circ\text{C}$
- Irradiation: $F(p) = 1.1 \cdot 10^{14} n_{\text{eq}}/\text{cm}^2$, $F(n) = 10^{14} n_{\text{eq}}/\text{cm}^2$
- Annealing: 10min@ 60°C

Charge collection 320 μm p-type (Y)

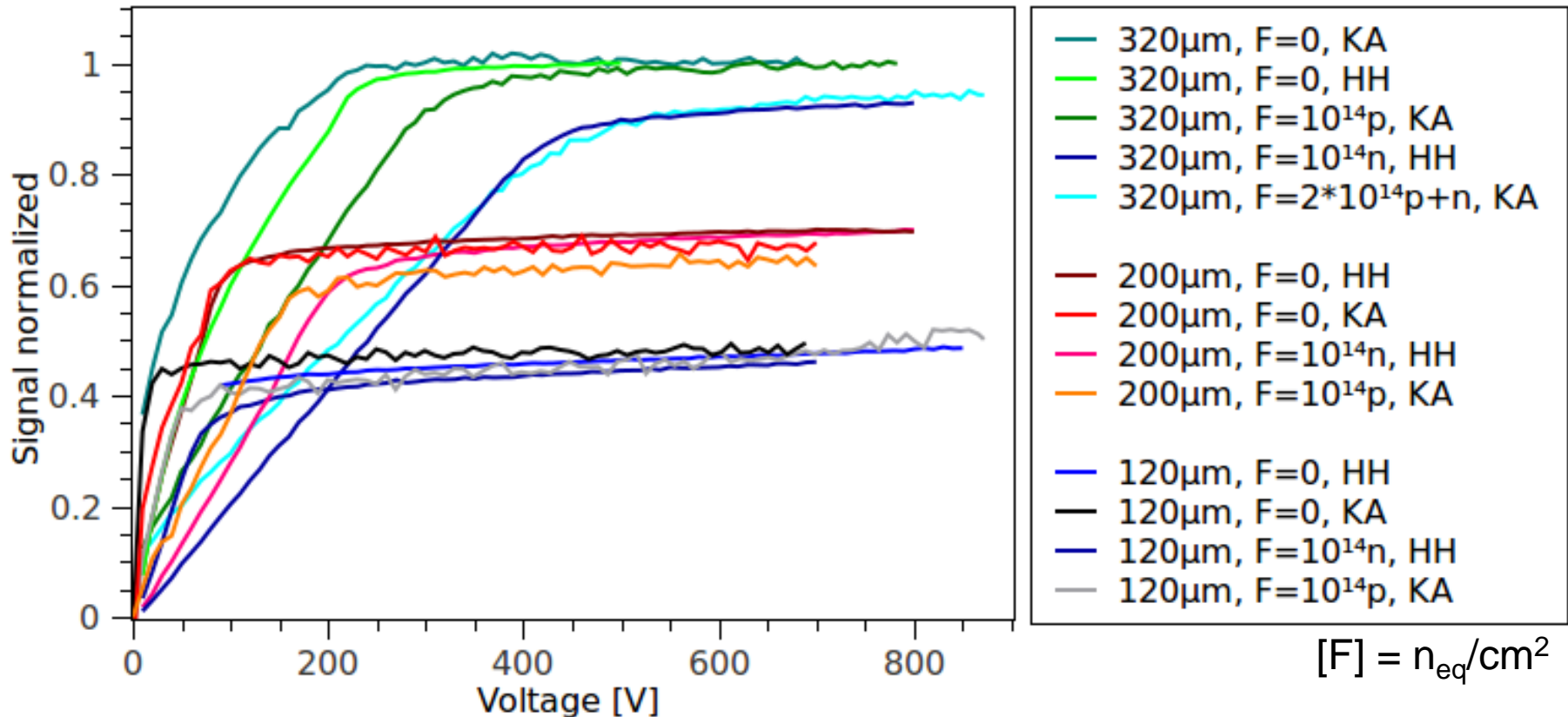


Charge collection 320 μm n-type (N)



CCE measurements of irradiated diodes

CCE p-type diodes (Y)

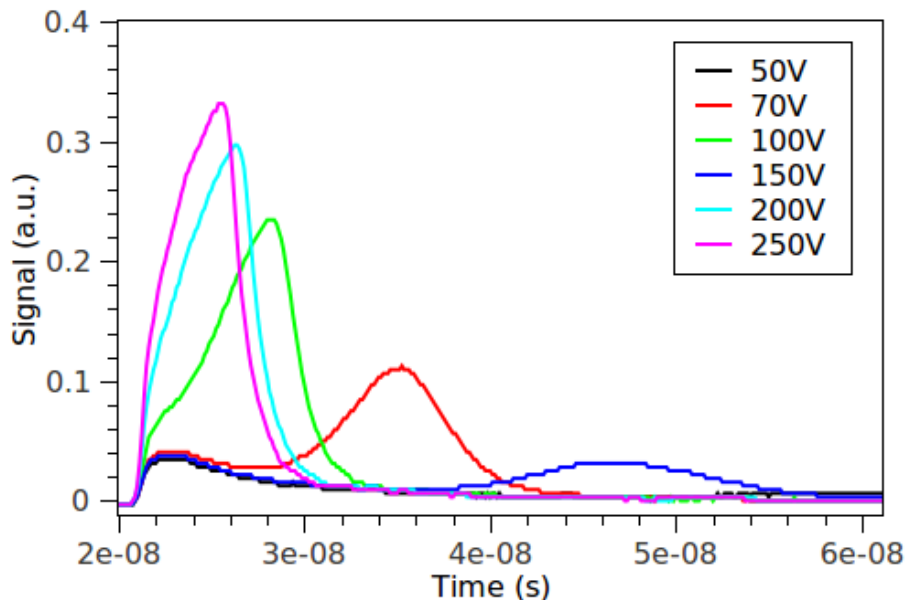


- Some diodes showed variation measuring several times - remeasure
- Different Setups at HH / KA in quite good agreement when normalized to 320µm thick diode
- Errors ±5%
- Different Annealing! KA: 10min@60°C, HH: 2h@RT

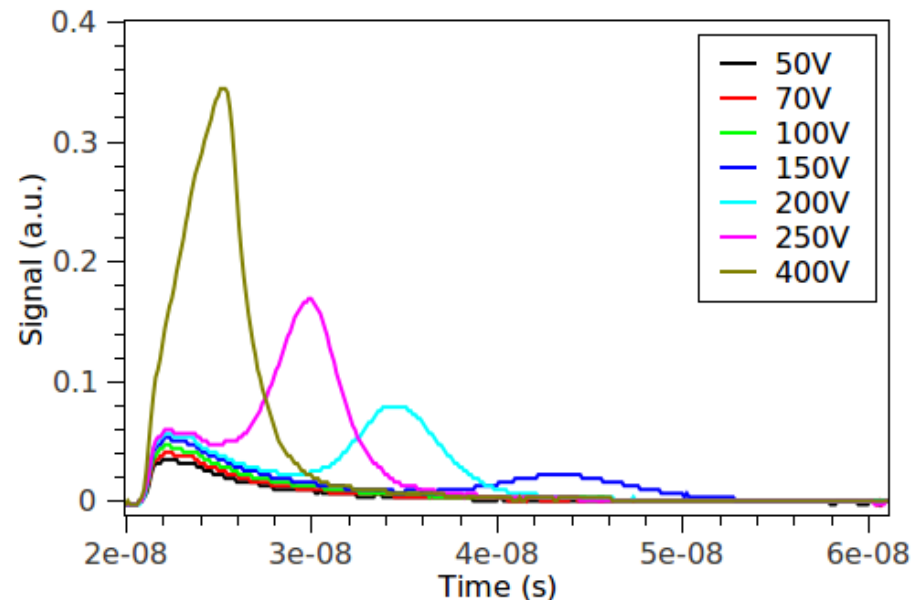
TCT measurements on irradiated diodes

- TCT measurements
- Signal shape of irradiated diodes
 - Red Laser (680nm)
- Here: Large 320 μm n-type diodes
- Very nice double peak for n-type diodes (electrons)
- Time resolution should improve with small diodes (lower capacitance)

TCT Signal FZ320N_08_DiodeL_05
 $F=1.1 \cdot 10^{14} \text{neq/cm}^2$ (p)

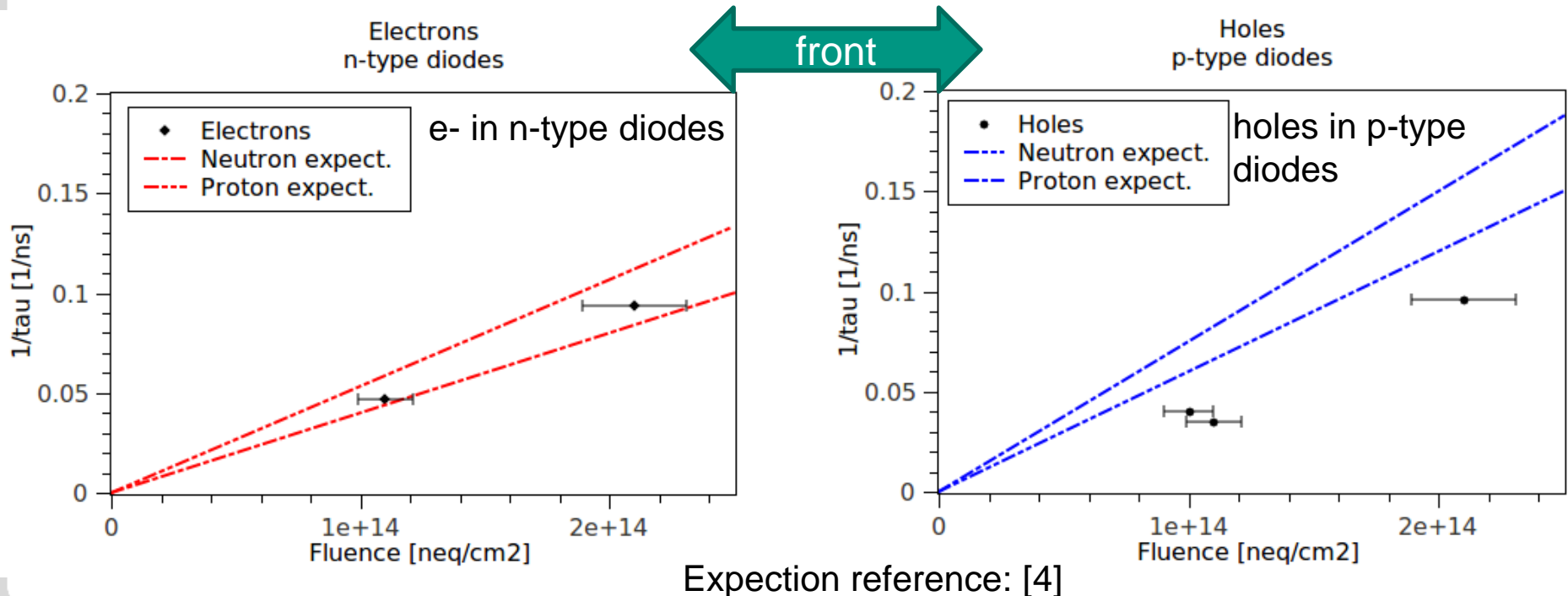


TCT Signal FZ320N_10_DiodeL_05
 $F=2.1 \cdot 10^{14} \text{neq/cm}^2$ (p+n)



TCT measurements on irradiated diodes

- Red Laser shot on frontside of diodes
- Trapping times calculated with charge correction method (CCM)
- Annealing: ~50h at RT
- Used model for effective trapping times:
- $I(t) = I_0(t) * e^{\left(\frac{t-t_0}{\tau}\right)}$
- What to do with thinner devices?

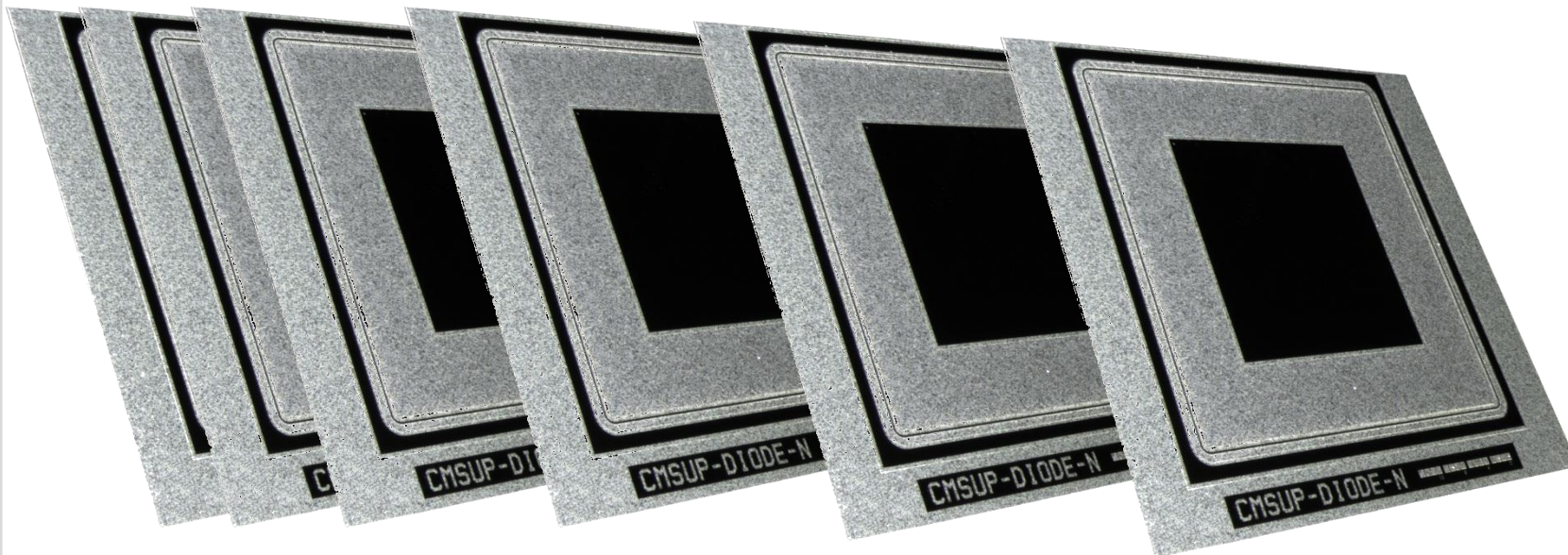


Summary and conclusions

- First irradiation of diodes successful (neutrons, protons, $F=10^{14}n_{eq}/cm^2$)
- Comparability of setups in last step (CCE) quite good
- Beginning investigations on TCT curves
- Trapping times: electrons fit to expected values, holes do not
 - More investigation necessary
 - Thin devices
 - Define method in the diode group to get trapping times (probably not CCM)

Outlook

- First standard irradiation of the CMS-HPK-Campaign soon
- More irradiations and additional irradiation steps for diodes
- More materials involved in next irradiations: FZ, MCz, Epi
- Start comparison of CCE of different materials, bulk dopings and mixed irradiation scenarios



THANK YOU FOR YOUR ATTENTION!

References

[1] Diode meeting, April 24th 2011, Thomas Pöhlsen; Institut für Experimentalphysik, Universität Hamburg.

<https://indico.cern.ch/conferenceDisplay.py?confId=132650>

[2] Sensor upgrade meeting, Feb. 17th 2011, Georg Steinbrück, Thomas Pöhlsen; Institut für Experimentalphysik, Universität Hamburg.

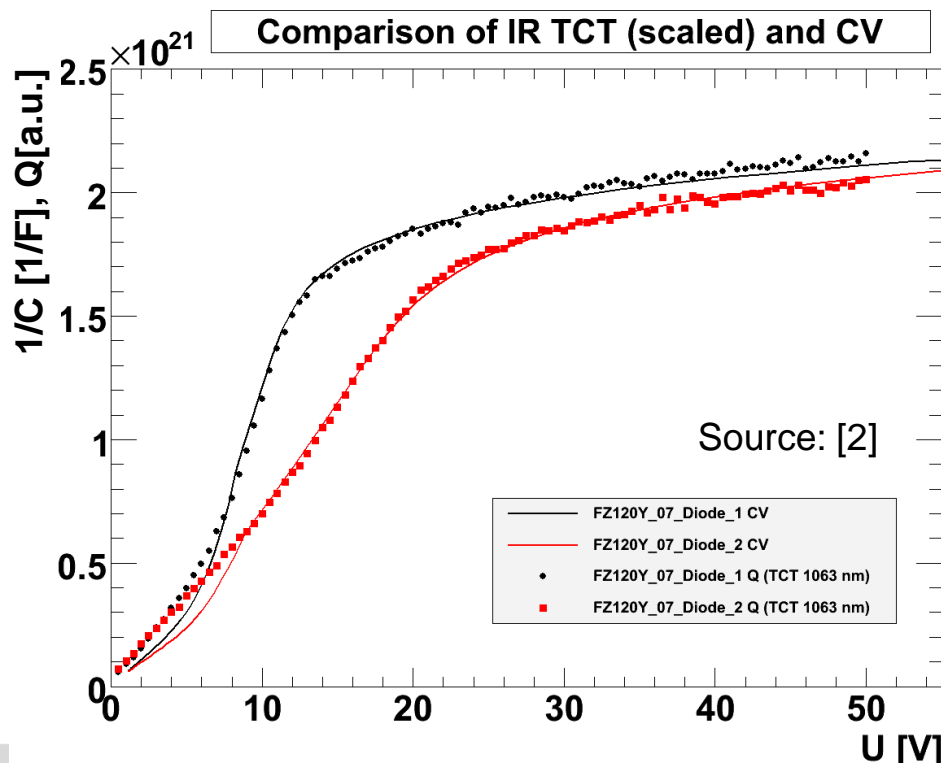
<https://indico.cern.ch/conferenceDisplay.py?confId=125774>

[3] Measurements of irradiated diodes, Christian Scharf; Institut für Experimentalphysik, Universität Hamburg.

[4] G. Kramberger et al., Nuclear Instruments and Methods in Physics Research A 481, 2002, 297-305

CCE measurement of unirradiated diodes

- CV and CC measurements are compared with respect to differences between Diode_1 and Diode_2 of the same wafer



- Collected charge: deposited charge in depleted volume + outdiffusing charge deposited in undepleted volume
- Neglecting diffusion
 - Q ~ depletion width ~ 1/C
- CCE determined with IR Laser from frontside
- No corrections for reflections or absorption
- CCE measurements confirm CV measurements qualitatively